TABLE 1

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label text</th>
</tr>
</thead>
<tbody>
<tr>
<td>001</td>
<td>ChangeRef</td>
</tr>
<tr>
<td>002</td>
<td>ChangeRef</td>
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</tbody>
</table>

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE

BOARD #: XX7896

REVs: E1

SUN REV: Not In VersionControl

IGNORE -> Top Overlay

PLOT NAME = Top Assembly Drawing

GENERATED: 3/6/2013 8:33:40 AM

TEXAS INSTRUMENTS
COMPONENTS MARKED ‘DNP’ SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
ASSEMBLY VARIANT: DD1

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: XX7896</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td>IGNORE -&gt;</td>
<td>Bottom 0.6519m</td>
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</table>

PLOT NAME = Bottom Assembly Drawing  GENERATED : 3/6/2013  8:33:41 AM  TEXAS INSTRUMENTS
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